

Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

Product Description

[Printed Circuit Board Manufacturer](#)

[pcb board manufacturer china](#)

[Pcb prototype manufacturer china](#)

Quick Details

Place of Origin	Guang Dong, China (mainland)	Brand Name	O-Leading
Basic Material	En-4, aluminum	Copper Thickness	0.5 oz-oz
Min. Hole Size	0.2 mm	Min. line width	0.2 mm
Surface Finishing	Gold immersion, OSP, lead free Hasl	Thickness of Board	0.1 to 5 mm
Applicable to	LED, cell phone, air Conditioners, Washing machines	Character	Industrial Control PCB
Certificates	ISO9001, UL, RoHS, SGS	Q/CTN	10pcs-100pcs
Weight	0.01 kg-5 kg	Moq	10pcs
Color	Blue, red, green, black. Yellow	Price	\$0.1-\$ 10
Model number	Power Bank PCB Assembly PCBA Manufacturer	Size	0.01 M3-10
Type of Desigh	Customer's requirement	Min. Spacing of lines	0.2mm

Packaging and Delivery

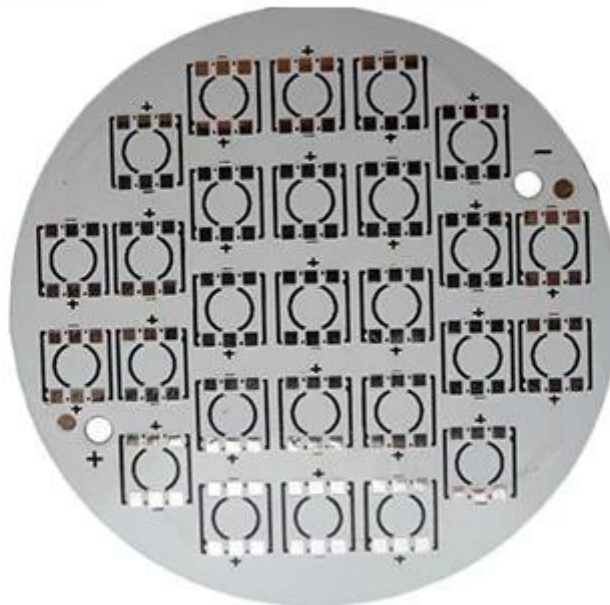
Packing Details:	16 years professional PCB OEM Card manufacturer
Delivery details	7-12days

Description of the Product

16 years professional OEM PCB board manufacture

Point	2014		2015 ~ 2016		2017 ~ 2018	
	Volume	Sample	Volume	Sample	Volume	Sample

Number of layers	32	42	38	44	42	48
Min/Space line (μm)	50/50	40/45	40/45	40/40	35/40	35/35
Min Drill Hole Diameter (mm)	0.15	0.10	0.15	0.10	0.15	0.10
Aspect ratio of PTH	14:1	16:1	16:1	18:1	18:1	20:1
n + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Any layer Interconnection	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Plate filling by	Yes	--	Yes	--	Yes	--
Min. Core thickness (Exclude copper) μm	50	40	40	30	40	30
Min Laser drill. Diameter (μm)	75	65	65	50	50	40
Via on buried Hole/stacked via	Yes	--	Yes	--	Yes	--
Material	FR4, Megtron, Nelco, Rogers, heavy copper, etc.					
Integrated Capacitor PCB	Yes	--	Yes	--	Yes	--
Surface process	Lead-free HASL, Enig, OSP, immersion silver, immersion tin, Gold of flash, gold finger plating, selective hard gold Plating, Peelable welding mask, carbon ink					



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Our Team





Certifications



2017/26 201VQZ430354 - Wiring, Printed - Component

ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit UL's [eCRP Family of Databases](#).
Click on a product designation for complete information.

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Wiring, Printed - Component

[See General Information for Wiring, Printed - Components](#)

O-LEADING SUPPLY CHAIN CO LIMITED E490354
Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

	Cond Width		Cond	SS/	Area	Solder	Oper	Temp	Flame	UL796	C
	Min	Max									
Typ	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
Huizhou (mass laminate) printed wiring boards.											
O-LEADING-401											
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	12.7 (0.5)	260	10	230	V-0	-	-
O-LEADING-407											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	D5	9.7 (0.4)	260	10	170	V-0	AB	-
Huizhou printed wiring boards.											
O-LEADING-408											
	0.125 (0.005)	0.125 (0.005)	12 (0.47)	D6	50.8 (2.0)	260	20	130	V-0	AB	-
Single layer printed wiring boards.											
O-LEADING-002											
	0.76 (0.015)	1.14 (0.045)	34 (1.34)	D5	19.1 (0.8)	260	10	105	V-0	AB	-
O-LEADING-003											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	D5	19.1 (0.8)	260	10	130	V-0	AB	-
O-LEADING-033											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	D5	25.4 (1.0)	260	10	120	V-0	AB	-
O-LEADING-205											
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	69.8 (2.7)	260	10	130	V-0	AB	-
O-LEADING-206											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	D5	69.8 (2.7)	260	10	130	V-0	AB	-

* - CTT marking is optional and may be marked on the printed wiring board.

Making: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test designation.
Last updated on 2017-01-27

Questions? [Print this page](#) [Terms of Use](#) [Page Top](#)

[Implications of using this information for the purpose of the ZPMV2.E490354 - Wiring, Printed - Component](#)



Test Report No. CAVE1805164701 Date: 03 Apr 2018 Page 2 of 8

Test Results:

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	CAN18-051647.001	Green "PCB"

- Remarks:
- (1) 1 mg/kg = 1 ppm = 0.0001%
 - (2) MDL = Method Detection Limit
 - (3) ND = Not Detected (< MDL)
 - (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Trisbromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND
Hexabromodiphenyl ether	-	mg/kg	5	ND
Heptabromodiphenyl ether	-	mg/kg	5	ND
Octabromodiphenyl ether	-	mg/kg	5	ND
Nonabromodiphenyl ether	-	mg/kg	5	ND
Decabromodiphenyl ether	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Trisbromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

SGS Testing Laboratory (Shanghai) Co., Ltd. is a member of the SGS Group. The SGS Group is a leading provider of inspection, testing, and certification services. The SGS Group is committed to providing high-quality services to its customers. The SGS Group is a member of the ISO 9001:2015 standard.

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Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days



FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching → Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.